

ACS280MS

Radiation Hardened 9-Bit Odd/ Even Parity Generator Checker

January 1996

Features

- Devices QML Qualified in Accordance with MIL-PRF-38535
- Detailed Electrical and Screening Requirements are Contained in SMD# 5962-96708 and Intersil' QM Plan
- 1.25 Micron Radiation Hardened SOS CMOS
- Single Event Upset (SEU) Immunity: <1 x 10⁻¹⁰ Errors/Bit/Day (Typ)

- Dose Rate Survivability.....>10¹² RAD (Si)/s, 20ns Pulse
- Latch-Up Free Under Any Conditions
- Military Temperature Range-55°C to +125°C
- Significant Power Reduction Compared to ALSTTL Logic
- DC Operating Voltage Range 4.5V to 5.5V
- Input Logic Levels
 - VIL = 30% of VCC Max
 - VIH = 70% of VCC Min
- Input Current \leq 1µA at VOL, VOH
- Fast Propagation Delay..... 23ns (Max), 15ns (Typ)

Description

The Intersil ACS280MS is a Radiation Hardened 9-bit odd/even parity generator checker device. Both odd and even parity outputs are available for generating or checking parity for words up to 9 bits long. Even parity is indicated (EVEN output high) when an even number of data inputs are high. Odd parity is indicated (ODD output high) when an odd number of data inputs are high. Parity checking for larger words can be accomplished by tying EVEN output to any input of an additional ACS280MS.

The ACS280MS utilizes advanced CMOS/SOS technology to achieve high-speed operation. This device is a member of a radiation hardened, high-speed, CMOS/SOS Logic Family.

The ACS280MS is supplied in a 14 lead Ceramic Flatpack (K suffix) or a Ceramic Dual-In-Line Package (D suffix).



Ordering Information

PART NUMBER	TEMPERATURE RANGE	SCREENING LEVEL	PACKAGE
5962F9670801VCC	-55°C to +125°C	MIL-PRF-38535 Class V	14 Lead SBDIP
5962F9670801VXC	-55°C to +125°C	MIL-PRF-38535 Class V	14 Lead Ceramic Flatpack
ACS280D/Sample	25°C	Sample	14 Lead SBDIP
ACS280K/Sample	25°C	Sample	14 Lead Ceramic Flatpack
ACS280HMSR	25°C	Die	Die

CAUTION: These devices are sensitive to electrostatic discharge; follow proper IC Handling Procedures. 1-888-INTERSIL or 321-724-7143 | Intersil (and design) is a trademark of Intersil Americas Inc. Copyright © Intersil Americas Inc. 2002. All Rights Reserved 1



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Die Characteristics

DIE DIMENSIONS

88 mils x 88 mils 2.24mm x 2.24mm

METALLIZATION:

Type: AlSi Metal 1 Thickness: 7.125kÅ ±1.125kÅ Metal 2 Thickness: 9kÅ ±1kÅ

GLASSIVATION:

Type: SiO₂ Thickness: 8kÅ ±1kÅ

WORST CASE CURRENT DENSITY: $<2.0 \times 10^5 \text{ A/cm}^2$

BOND PAD SIZE:

> 4.3 mils x 4.3 mils

> 110µm x 110µm

Metallization Mask Layout



